

1U CloudDC with 10 hot-swap 2.5" NVMe/SAS/SATA bays and 2 PCIe 5.0 x16 slots + 2 AIOM slots

## **Key Applications**

Web Server, Firewall Application, Data Center Optimized, Value IaaS, Cloud Computing, Compact Server, DNS & Gateway Servers, Firewall Application, CDN, Edge Nodes,

## **Key Features**

- Single AMD EPYC<sup>™</sup> 9004/9005\* Series Processor (\*AMD EPYC<sup>™</sup> 9005 series drop-in support requires board revision 2.x);
- Support up to DDR5 12 DIMM slots (1DPC);
- 2 PCIe 5.0 x16 FHHL;
- Dual AIOM (OCP 3.0) for networking, 1 dedicated IPMI LAN;
- 10 Hot-swap 2.5" SATA drive bays Optional 10 Hot-swap NVMe/SAS drives support via additional parts 2 M.2 PCIe 3.0 x2 NVMe slots;
- Dual 860W redundant power supplies (Power supply full redundancy based on configuration and application load);



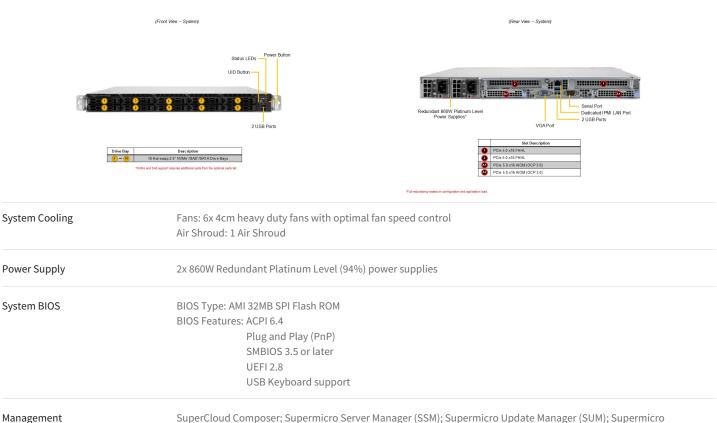
Form Factor	1U Rackmount Enclosure: 437 x 43 x 597mm (17.2" x 1.7" x 23.5") Package: 605 x 197 x 822mm (23.8" x 7.8" x 32.4")
Processor	Single processor(s) AMD EPYC™ 9004/9005 Series Processors (* AMD EPYC™ 9005 Series drop-in support requires board revision 2.x) Up to 160C/320T
GPU	Max GPU Count: Up to 2 single-width GPUs Supported GPU: NVIDIA PCIe: L4, A2 CPU-GPU Interconnect: PCIe 5.0 x16 CPU-to-GPU Interconnect GPU-GPU Interconnect: PCIe
System Memory	Slot Count: 12 DIMM slots Max Memory (1DPC): Up to 3TB 4800MT/s ECC DDR5 RDIMM (AMD EPYC™ 9004 Series Processor) Max Memory (1DPC): Up to 4.5TB 6000MT/s ECC DDR5 RDIMM (AMD EPYC™ 9005 Series Processor)
Drive Bays Configuration	Default: Total 10 bays • 10 front hot-swap 2.5" SATA drive bays Option A: Total 10 bays • 10 front hot-swap 2.5" PCIe 5.0 NVMe* drive bays Option B: Total 10 bays • 10 front hot-swap 2.5" SAS* drive bays (*NVMe/SAS support may require additional storage controller and/or cables, please see the optional parts list for details) M.2: 2 M.2 PCIe 3.0 x2 NVMe slots (M-key 2280/22110)
Expansion Slots	Default • 2 PCIe 5.0 x16 FHHL slots • 2 PCIe 5.0 x16 AIOM slots (OCP 3.0 compatible)
On-Board Devices	Chipset: System on Chip Network Connectivity: Via AIOM
Input / Output	LAN: 1 RJ45 1 GbE Dedicated BMC LAN port USB: 2 USB 3.0 ports(rear) 2 USB 2.0 ports(front) Video: 1 VGA port Serial: 1 COM port(Rear) TPM: 1 TPM header



More details







Chassis	CSE-LB16TS-R860AWP-A
otherboard	Super H13SSW
	Non-operating Relative Humidity: 5% to 95% (non-condensing)
	Operating Relative Humidity: 8% to 90% (non-condensing)
	Non-operating Temperature: -40°C to 60°C (-40°F to 140°F)
Operating Environment	Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F)
	Available Color: Black front & sliver body
	Net Weight: 25 lbs (11.3 kg)
Dimensions and Weight	Weight: Gross Weight: 46 lbs (20.9 kg)
	thermal trip support
	System temperature, Memory temperature, CPU temperature, 3.3V standby, +5V standby, +5V, +3.3V, +12V, CPU
	Voltage:
	Thermal Control for fan connectors
	Temperature: Monitoring for CPU and chassis environment
	Pulse Width Modulated (PWM) fan connectors
	Status monitor for speed control
PC Health Monitoring	FAN: Fans with tachometer monitoring
	Package (SFT-OOB-LIC ); SuperServer Automation Assistant (SAA) New!
	SuperDoctor <sup>®</sup> 5 (SD5); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); OOB Management
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Supermicro Opdate Manager (SOM); Supermicro